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PTO/SB/08a/b (08-03)

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Substitute for form 1449A/B/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

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of

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Complete if Known	
Application Number	10/614,067 (Conf. No. 8117)
Filing Date	July 3, 2003
First Named Inventor	Leedy
Art Unit	2822
Examiner Name	Pamela Perkins
Attorney Docket Number	ELM-2 Div. 6

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite's No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Examiner Signature	/Pamela Perkins/	Date Considered	05/08/2006
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Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.				T ²
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PEP		Wolf, Stanley and Richard N. Tauber; Silicon Processing For the VLSI Era, Volume 1: Process Technology, Sunset Beach, CA: Lattice Press, 1986, pages 191-194				

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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹Applicant's unique citation designation number (optional). ²See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 801.04. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶Applicant is to place a check mark here if English language Translation is attached.

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